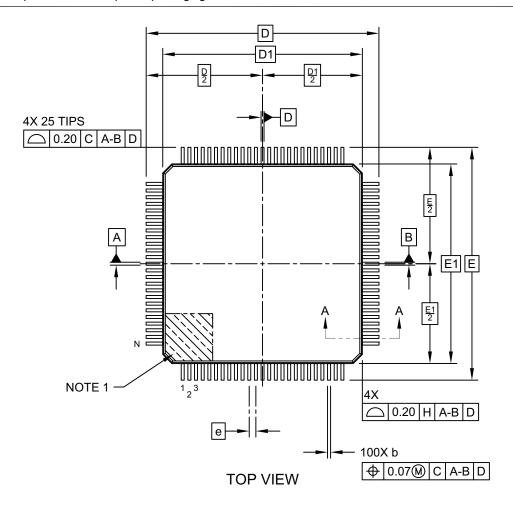
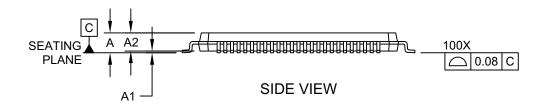


100-Lead Plastic Thin Quad Flatpack (PT) - 12x12x1 mm Body [TQFP] 2.00 mm Footprint

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



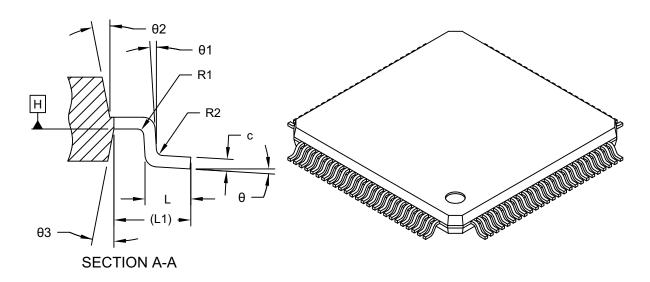


Microchip Technology Drawing C04-100-PT Rev C Sheet 1 of 2



100-Lead Plastic Thin Quad Flatpack (PT) - 12x12x1 mm Body [TQFP] 2.00 mm Footprint

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS			
Dimension Limits		MIN	NOM	MAX	
Number of Leads	N	100			
Lead Pitch	е	0.40 BSC			
Overall Height	Α	1	_	1.20	
Standoff	A1	0.05	_	0.15	
Molded Package Thickness	A2	0.95	1.00	1.05	
Overall Length	D	14.00 BSC			
Molded Package Length	D1	12.00 BSC			
Overall Width	E	14.00 BSC			
Molded Package Width	E1	12.00 BSC			
Foot Length	L	0.45	0.60	0.75	
Footprint	L1	1.00 REF			
Lead Width	b	0.13	0.18	0.23	
Lead Thickness	С	0.09	_	0.20	
Lead Bend Radius	R1	0.08	_	_	
Lead Bend Radius	R2	0.08	_	0.20	
Foot Angle	θ	0°	_	7°	
Lead Angle	θ1	0°	_	_	
Mold Draft Angle	θ2	11°	12°	13°	
Mold Draft Angle	θ3	11°	12°	13°	

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

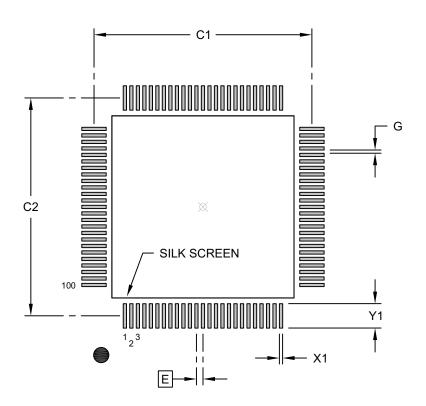
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-100-PT Rev C Sheet 2 of 2



100-Lead Plastic Thin Quad Flatpack (PT) - 12x12x1 mm Body [TQFP] 2.00 mm Footprint

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS			
Dimension Limits		MIN	NOM	MAX	
Contact Pitch	Е	0.40 BSC			
Contact Pad Spacing	C1		13.40		
Contact Pad Spacing	C2		13.40		
Contact Pad Width (X100)	X1			0.20	
Contact Pad Length (X100)	Y1			1.50	
Contact Pad to Contact Pad (X96)	G	0.20			

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2100-PT Rev C